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authored over 210 papers. He has given over 50 invited/keynote talks and given several Seminars. He received NY IP Law association “Inventor of the year” award in February 2020. He was awarded prestigious IEEE Daniel Noble award fin 2018 for contributions to predictive analytics, circuits and technology. He received Industrial Pioneer award 2014 from IEEE Circuits and Systems society. He received the Best Editor Award from IEEE TVLSI journal. He was inducted into New Jersey Inventor Hall of Fame in Aug 2014. He is a recipient of 2013 IEEE CAS Industrial Pioneer award and 2013 Mehboob Khan Award from Semiconductor Research Corporation. He won this award again in 2020 for AI initiatives in BRIC program funded by SRC. He won several best paper awards from ISSCC 1992, ICCAD 2012, ISQED, VMIC. He is a member of IBM Academy of Technology and a Master Inventor. He serves on the Board of Governors for IEEE CAS as Industrial Liaison. He served as a Distinguished Lecturer for IEEE CAS, CEDA and EDS society. He is IEEE, ISQED and World Technology Network Fellow and Distinguished Alumnus of IIT Bombay. He serves as an Associate Editor of TVLSI and TCAS I journals. He has served on committees of conferences such as DAC 2019, AICAS 2019, ISCAS, ISLPED (Int. Symposium Low Power Electronic Design), IEEE VLSI design, IEEE CICC, IEEE Int. SOI conference, ISQED and Advanced Metallization. He is an Industry Liaison for universities as a part of the Semiconductor Research Corporation and IEEE CAS society.